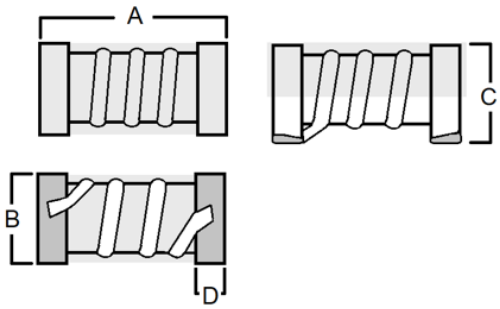
High Frequency Winding Type Chip Inductor SWI0402HO-SERIES

1. Features

1. Ceramic core wire wound construction.
2. No batch to batch variations in inductance.
3. High Reliability due to ceramic wire wound construction.
4. High frequency application.
5. Small footprint as well as low profile.
6. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
7. Operating temperature-40~+125℃ (Including self - temperature rise).

2. Dimensions



Size	A(mm)	B(mm)	C(mm)	D(mm)
SWI0402	1.00±0.20	0.60±0.20	0.56±0.10	0.20±0.10

Unit: mm

3. Part Numbering

SWI	0402	H	O	-	2N2	B
A	B	C	D		E	F

A: Series
B: Dimension LxW
C: Material 4H Core
D: Category Code Industrial Grade
E: Inductance 2N2=2.2nH
F: Inductance Tolerance B=±0.1nH, C=±0.2nH, S=±0.3nH, G=±2%, J=±5%, K=±10%

4. Specification

Part Number	Inductance (nH)	Tolerance	Test Frequency (Hz)	Q Typ.	Test Frequency	Rated Current (mA) max.	DCR (Ω) max.	SRF (GHz) Typ.
SWI0402HO-2N2□	2.2	B,C,S	0.1V/100M	30	0.1V/250M	2530	0.022	15.5
SWI0402HO-2N4□	2.4	B,C,S	0.1V/100M	30	0.1V/250M	2530	0.022	15.5
SWI0402HO-3N0□	3.0	B,C,S	0.1V/100M	20	0.1V/250M	1350	0.063	12.5
SWI0402HO-3N3□	3.3	B,C,S	0.1V/100M	30	0.1V/250M	2000	0.030	14.0
SWI0402HO-3N6□	3.6	B,C,S	0.1V/100M	30	0.1V/250M	1950	0.030	10.0
SWI0402HO-3N9□	3.9	B,C,S	0.1V/100M	35	0.1V/250M	1950	0.030	10.0
SWI0402HO-4N1□	4.1	B,C,S	0.1V/100M	30	0.1V/250M	1800	0.044	9.6
SWI0402HO-4N5□	4.5	B,C,S	0.1V/100M	34	0.1V/250M	1450	0.060	9.6
SWI0402HO-4N8□	4.8	B,C,S	0.1V/100M	30	0.1V/250M	1200	0.071	8.0
SWI0402HO-5N0□	5.0	B,C,S	0.1V/100M	32	0.1V/250M	1770	0.040	10.0
SWI0402HO-5N5□	5.5	G,J,K	0.1V/100M	35	0.1V/250M	1770	0.040	8.0

Part Number	Inductance (nH)	Tolerance	Test Frequency (Hz)	Q Typ.	Test Frequency	Rated Current (mA) max.	DCR (Ω) max.	SRF (GHz) Typ.
SWI0402HO-6N0□	6.0	G,J,K	0.1V/100M	32	0.1V/250M	1770	0.056	8.0
SWI0402HO-6N8□	6.8	G,J,K	0.1V/100M	30	0.1V/250M	1450	0.068	7.0
SWI0402HO-7N3□	7.3	G,J,K	0.1V/100M	32	0.1V/250M	1700	0.050	7.0
SWI0402HO-7N5□	7.5	G,J,K	0.1V/100M	32	0.1V/250M	1700	0.050	7.0
SWI0402HO-8N2□	8.2	G,J,K	0.1V/100M	32	0.1V/250M	1500	0.069	6.5
SWI0402HO-8N7□	8.7	G,J,K	0.1V/100M	31	0.1V/250M	1420	0.070	6.5
SWI0402HO-9N0□	9.0	G,J,K	0.1V/100M	30	0.1V/250M	1420	0.070	6.5
SWI0402HO-10N□	10.0	G,J,K	0.1V/100M	31	0.1V/250M	1400	0.081	6.0
SWI0402HO-11N□	11.0	G,J,K	0.1V/100M	32	0.1V/250M	1400	0.083	6.2
SWI0402HO-12N□	12.0	G,J,K	0.1V/100M	30	0.1V/250M	1240	0.093	5.2
SWI0402HO-13N□	13.0	G,J,K	0.1V/100M	30	0.1V/250M	1240	0.093	5.2
SWI0402HO-15N□	15.0	G,J,K	0.1V/100M	31	0.1V/250M	1150	0.114	5.5
SWI0402HO-18N□	18.0	G,J,K	0.1V/100M	30	0.1V/250M	1050	0.130	5.2
SWI0402HO-23N□	23.0	G,J,K	0.1V/100M	29	0.1V/250M	760	0.201	4.5
SWI0402HO-27N□	27.0	G,J,K	0.1V/100M	30	0.1V/250M	680	0.288	4.0
SWI0402HO-30N□	30.0	G,J,K	0.1V/100M	30	0.1V/250M	660	0.309	3.8
SWI0402HO-33N□	33.0	G,J,K	0.1V/100M	30	0.1V/250M	620	0.336	3.6
SWI0402HO-36N□	36.0	G,J,K	0.1V/100M	30	0.1V/250M	540	0.431	3.5
SWI0402HO-47N□	47.0	G,J,K	0.1V/100M	25	0.1V/200M	440	0.648	3.2
SWI0402HO-56N□	56.0	G,J,K	0.1V/100M	25	0.1V/200M	340	0.996	2.9

Note:

- All test data referenced to 25℃ ambient.
- DC current at 25°C that causes the specified inductance drop from its value without current.
- Current that causes the specified temperature rise from 25°C ambient.

This information is for reference only and does not represent absolute maximum ratings.

5. Recommended PC Board Pattern

Chip size						Land Patterns For Reflow Soldering		
Series	Type	A(mm)	B(mm)	C(mm)	D(mm)	L(mm)	G(mm)	H(mm)
SWI	0402	1.00±0.20	0.60±0.20	0.56±0.10	0.20±0.10	1.42	0.60	0.66

